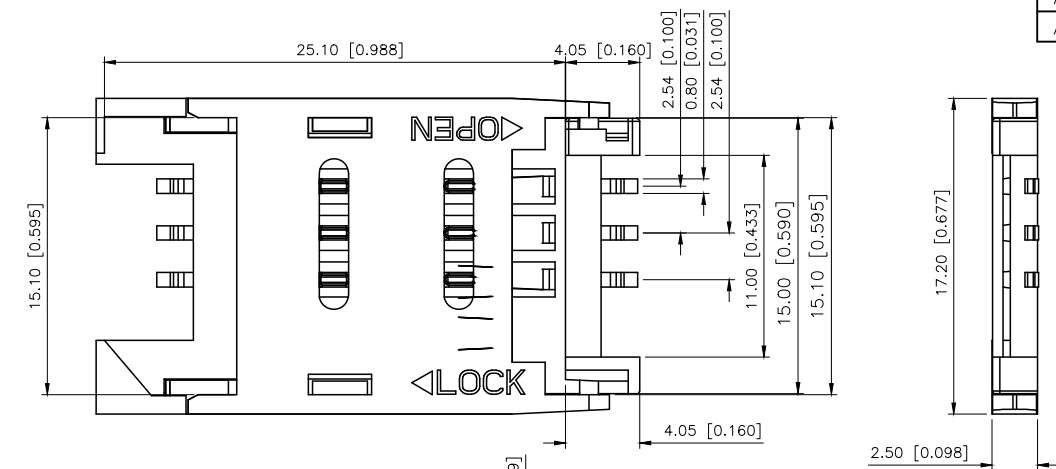
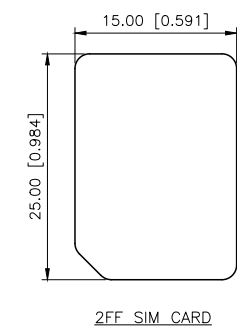
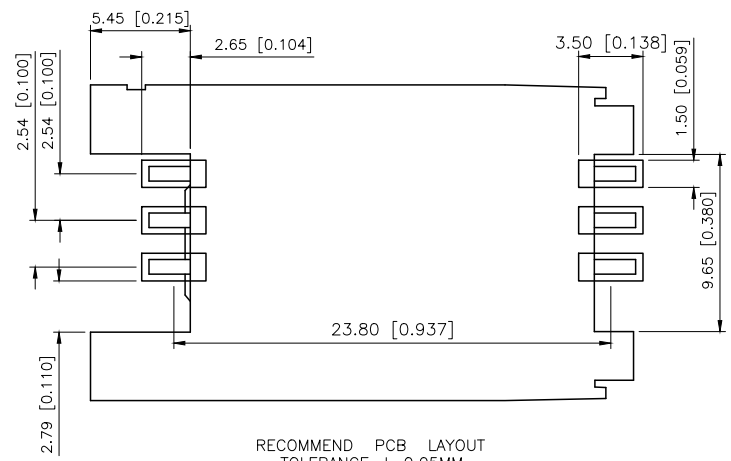
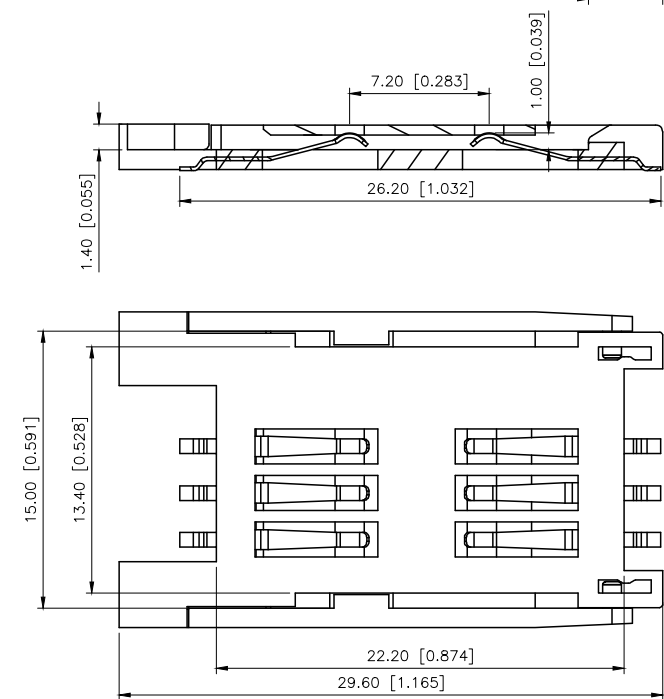


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.15	阿树



A.Material:
1.Insulator: Hing temperature thermoplastic
UL94V-0(BLACK LCP)
2.Pho.Bronze: Plating,40u"MIN nikel underplated
CONTACT AREA: Au 1u"
SOLDER AREA: 80u" TIN
B.Electrical specifications
Voltage rating: 12V AC
Current rating: 0.5A
Dielectric strength: 250V AC for 1 minute min
Insulation resistance: 500MΩ
Contact resistance: 50mΩ max
Operation, temperature: -40° TO 105
Product withstanding rflow soldering 260 for 10S
C.Mechanical specifications: Durability: 5000cycles



AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERAuces	



DESIGN	阿树	VIEW:		MODEL TYPE:	SIM CARD CONN
CHECKED		UNIT:	mm/in	PART NO.:	XKSIM-010
APPROVED		SIZE:	A4	DWG NO.:	